DATA SHEET

MOS FIELD EFFECT TRANSISTOR 2SK2138, 2SK2138-Z

SWITCHING **N-CHANNEL POWER MOS FET INDUSTRIAL USE**

DESCRIPTION

The 2SK2138, 2SK2138-Z is N-channel Power MOS Field Effect Transistor designed for high voltage switching applications.

FEATURES

• Low On-state Resistance

 $R_{DS(on)} = 2.4 \Omega MAX. (V_{GS} = 10 V, I_D = 2.5 A)$

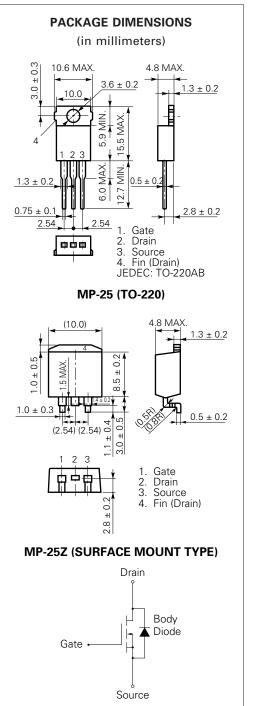
- Low Ciss Ciss = 550 pF TYP.
- High Avalanche Capability Ratings

ABSOLUTE MAXIMUM RATINGS (TA = 25 °C)

-		-	
Drain to Source Voltage	VDSS	600	V
Gate to Source Voltage	Vgss	±30	V
Drain Current (DC)	D(DC)	±5.0	А
Drain Current (pulse)*	D(pulse	e) ±20	А
Total Power Dissipation (T _c = 25 $^{\circ}$ C)	P T1	70	W
Total Power Dissipation (T _A = 25 $^{\circ}$ C)	Рт2	1.5	W
Storage Temperature	Tstg	–55 to +150	°C
Channel Temperature	T_{ch}	150	°C
Single Avalanche Current**	las	14	А
Single Avalanche Energy**	Eas	8.3	mJ
* $PW < 10 \mu s$ Duty Cycle < 1 %			

PW \leq 10 μ s, Duty Cycle \leq 1 %

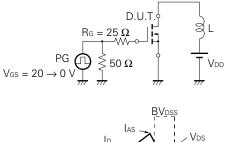
** Starting T_{ch} = 25 °C, R_G = 25 Ω , V_{GS} = 20 V \rightarrow 0

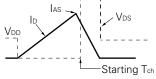


ELECTRICAL CHARACTERISTICS (TA = 25 °C)

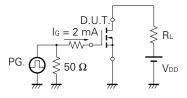
CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
Drain to Source On-state Resistance	RDS(on)		2.0	2.4	Ω	$V_{GS} = 10 \text{ V}, \text{ Id} = 2.5 \text{ A}$
Gate to Source Cutoff Voltage	V _{GS(off)}	2.5		3.5	V	$V_{DS} = 10 V, I_{D} = 1 mA$
Forward Transfer Admittance	y _{fs}	1.0			S	$V_{DS} = 10 V, I_{D} = 2.5 A$
Drain Leakage Current	loss			100	μΑ	$V_{DS} = 600 V, V_{GS} = 0$
Gate to Source Leakage Current	lgss			±100	nA	$V_{GS} = \pm 30 \text{ V}, \text{ V}_{DS} = 0$
Input Capacitance	Ciss		550		pF	$V_{DS} = 10 V$
Output Capacitance	Coss		130		pF	Vgs = 0
Reverse Transfer Capacitance	Crss		25		pF	f = 1 MHz
Turn-On Delay Time	td(on)		11		ns	$V_{GS} = 10 V$
Rise Time	tr		6.0		ns	$V_{DD} = 150 V$
Turn-Off Delay Time	td(off)		40		ns	I_{D} = 2.5 A, R_{G} = 10 Ω
Fall Time	tr		8		ns	$R_L = 60 \Omega$
Total Gate Charge	QG		20		nC	Vgs = 10 V
Gate to Source Charge	Qgs		4.0		nC	ID = 5.0 V
Gate to Drain Charge	Qgd		10		nC	V _{DD} = 450 V
Diode Forward Voltage	V _{F(S-D)}		1.0		V	IF = 5.0 A, VGS = 0
Reverse Recovery Time	trr		320		ns	IF = 5.0 A
Reverse Recovery Charge	Qrr		2.4		μC	di/dt = 50 A/µs

Test Circuit 1 Avalanche Capability

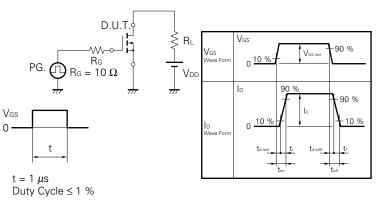




Test Circuit 3 Gate Charge

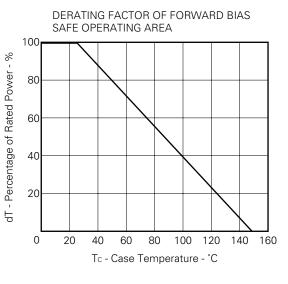


Test Circuit 2 Switching Time



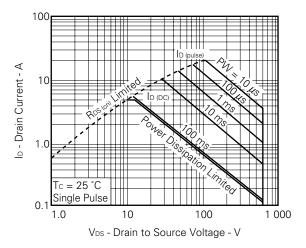
The application circuits and their parameters are for references only and are not intended for use in actual design-in's.

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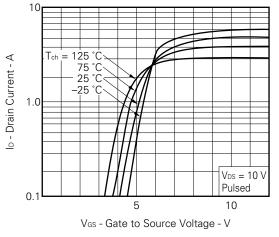


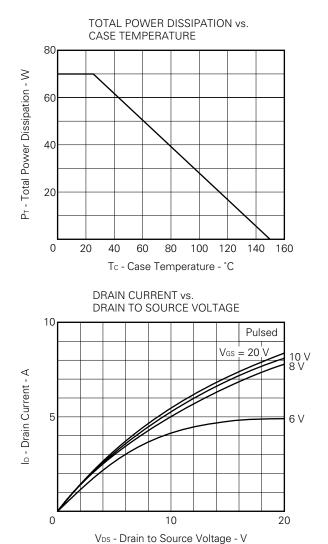


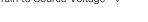


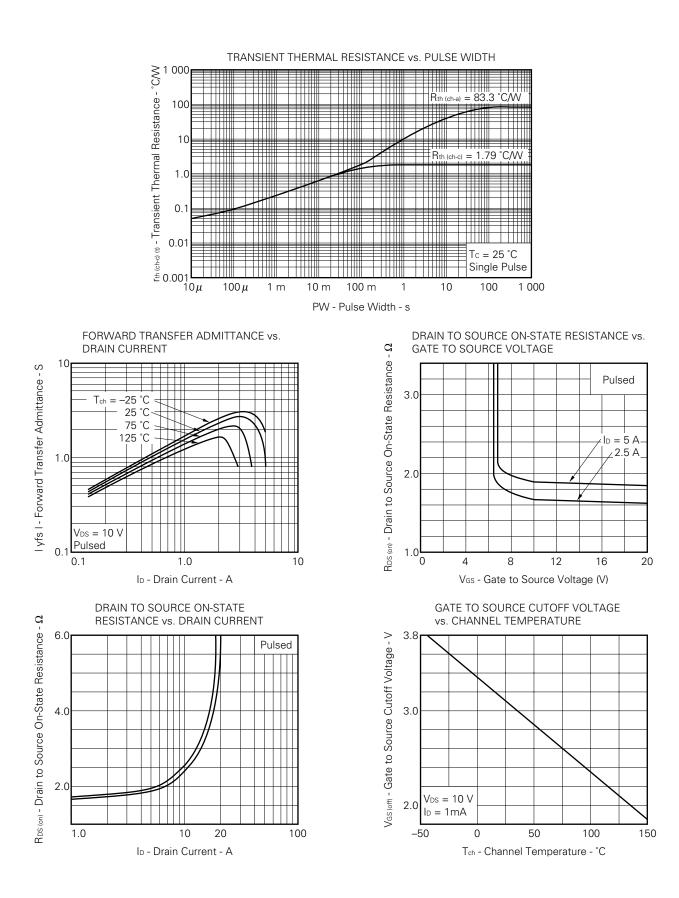


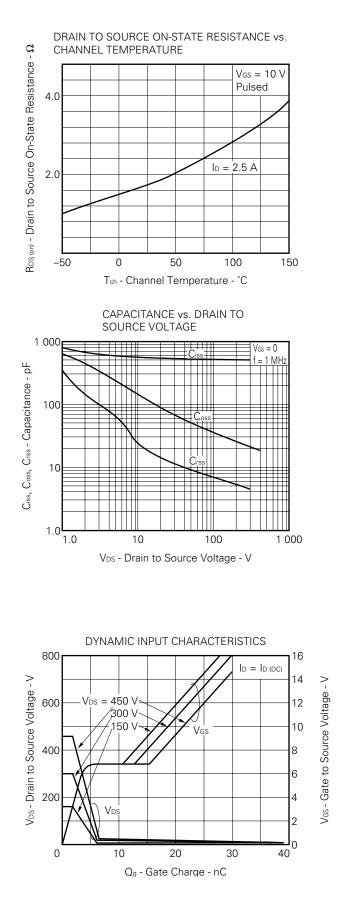


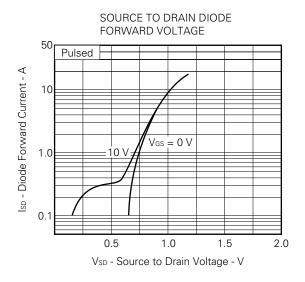




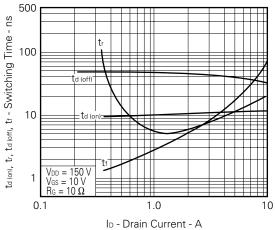


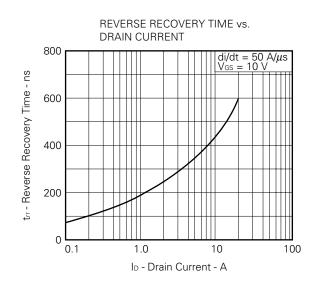


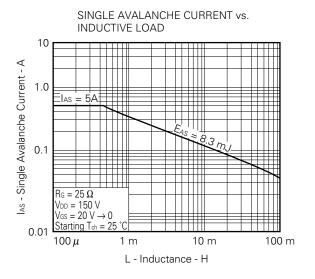


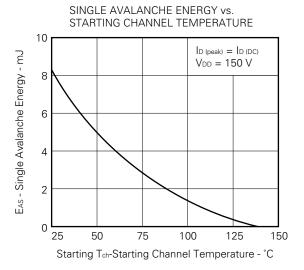












REFERENCE

Document Name	Document No.
NEC semiconductor device reliability/quality control system.	TEI-1202
Quality grade on NEC semiconductor devices.	IEI-1209
Semiconductor device mounting technology manual.	IEI-1207
Semiconductor device package manual.	IEI-1213
Guide to quality assurance for semiconductor devices.	MEI-1202
Semiconductor selection guide.	MF-1134
Power MOS FET features and application switching power supply.	TEA-1034
Application circuits using Power MOS FET.	TEA-1035
Safe operating area of Power MOS FET.	TEA-1037

The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device is actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

[MEMO]

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Anti-radioactive design is not implemented in this product.